

L Number	Hits	Search Text	DB	Time stamp
2	53446	substrate near5 bond\$3	USPAT; US-PGPUB	2003/05/11 17:17
3	38607	(substrate near5 bond\$3) and (remov\$3 detach\$3)	USPAT; US-PGPUB	2003/05/11 17:13
4	2959	((substrate near5 bond\$3) and (remov\$3 detach\$3)) and (metal near5 wir\$3)	USPAT; US-PGPUB	2003/05/11 17:17
5	2279	((((substrate near5 bond\$3) and (remov\$3 detach\$3)) and (metal near5 wir\$3)) and (insulat\$3 dielectric)	USPAT; US-PGPUB	2003/05/11 17:17
6	115	(remov\$3 separat\$3 detach\$3) near10 (metal near5 wire) near10 (base substrate)	USPAT; US-PGPUB	2003/05/11 14:54
7	168	(remov\$3 separat\$3 detach\$3) near10 (metal near5 wire) near10 (base substrate)	EPO; JPO; DERWENT; IBM_TDB	2003/05/11 14:55
8	33518	substrate near5 bond\$3	EPO; JPO; DERWENT; IBM_TDB	2003/05/11 17:13
9	3974	(substrate near5 bond\$3) and (remov\$3 detach\$3)	EPO; JPO; DERWENT; IBM_TDB	2003/05/11 17:13
10	924	((substrate near5 bond\$3) and (remov\$3 detach\$3)) and (insulat\$3 dielectric)	EPO; JPO; DERWENT; IBM_TDB	2003/05/11 17:13
11	24	((((substrate near5 bond\$3) and (remov\$3 detach\$3)) and (insulat\$3 dielectric)) and (metal near5 wir\$3))	EPO; JPO; DERWENT; IBM_TDB	2003/05/11 17:14
12	22356	connection near5 substrate	USPAT; US-PGPUB	2003/05/11 17:24
13	2372	(connection near5 substrate) and (metal near5 wir\$3)	USPAT; US-PGPUB	2003/05/11 17:24
14	2087	((connection near5 substrate) and (metal near5 wir\$3)) and (insulat\$3 dielectric)	USPAT; US-PGPUB	2003/05/11 17:18
15	1186	((((connection near5 substrate) and (metal near5 wir\$3)) and (insulat\$3 dielectric)) and glass	USPAT; US-PGPUB	2003/05/11 17:24
16	13250	connection near5 substrate	EPO; JPO; DERWENT; IBM_TDB	2003/05/11 17:24
17	276	(connection near5 substrate) and (metal near5 wir\$3)	EPO; JPO; DERWENT; IBM_TDB	2003/05/11 17:24
18	19	((connection near5 substrate) and (metal near5 wir\$3)) and glass	EPO; JPO; DERWENT; IBM_TDB	2003/05/11 17:24